Semiconductor Device Type: RPX 036 VQFN 6x6x0.9 Matte Tin			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)				JEDEC 97 Product Marking and/or Pkg. Labeling e3
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	26.10	(mg) Total	Mold Compound	% ot Total Weight	17.33
Silica, vitreous (or fused)	60676-86-0	Mold Compound	14.731	22.184	147,305		Silica, vitreous (or fused)	60676-86-0	85.00	
Epoxy Resin	Trade Secret	Mold Compound	1.508	2.271	15.077		Epoxy Resin	Trade Secret	8.70	
Phenolic Resin	Trade Secret	Mold Compound	1.040	1.566	10,398		Phenolic Resin	Trade Secret	6.00	
Carbon Black	1333-86-4	Mold Compound	0.052	0.078	520		Carbon Black	1333-86-4	0.30	
Copper	7440-50-8	Lead Frame	72.322	108.917	723,219			Total	100.00	
Iron	7439-89-6	Lead Frame	1.779	2.679	17,790	114.00	(mg) Total	Lead Frame	% of Total Weight	75.70
Silver	7440-22-4	Lead Frame	1.442	2,172	14,421		Copper	7440-50-8	95.54	
Zinc	7440-66-6	Lead Frame	0.095	0.143	946		Iron	7439-89-6	2.35	
Phosphorous	7723-14-0	Lead Frame	0.062	0.094	625		Silver	7440-22-4	1.91	
Silver	7440-22-4	Die Attach	0.143	0.215	1,425		Zinc	7440-66-6	0.13	
Epoxy resin	Trade Secret	Die Attach	0.048	0.072	475		Phosphorous	7723-14-0	0.08	
Silicon	7440-21-3	Chip (Die)	4.210	6.340	42,100			Total	100.00	
Copper	7440-50-8	Wire Bond	0.764	1.151	7,644	0.29	(mg) Total	Die Attach	% of Total Weight	0.19
Palladium	7440-05-3	Wire Bond	0.016	0.023	156	0.23	Silver	7440-22-4	75.00	0.15
Tin		Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	1.790	2.696	17,900		Epoxy resin	Trade Secret	25.00	
	7440-31-3	TOTALS:		150.600	1,000,000		Epoxy lesili	Total	23.00	
			100.000	150.600	1,000,000	6.34				4.21
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) and 2000/53/EC and 2016/774/EU (End-of-Life Vehicles (ELV pliance with the above EU Directives has been verified via in hemical substance is absent from the list above, the chemica rporated's knowledge and belief as of the date of this docum	y with EU Directives: 2 y without exemption (z ternal design controls, al substance is NOT ar ent, there is no credibl ry scheme world-wide. ability standard for pla	002/95/EC (27 January 2003) & Directive 2011/65/EU (08 ero) supplier declarations, and /or analytical test data. Intentional ingredient in the semiconductor device and, e reason to believe that the unavoidable impurity concen	to the best o stration of the	f Microchip Te chemical sub	echnology	1.17	Doped Silicon	7440-21-3 Total	100.00 100.00	0.78
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